



**Notes:**

- 1000ucd = 1 mcd, 1000mcd = 1 cd
- All dimensions are in millimeter
- Clean only in isopropanol, ethanol, Freon TF (or equivalent)
- If forming is required, it must be done before soldering . Form pin leads by securing under 5mm from body and bedding with radio pliers or the equivalent to avoid pressure on resin. When the LED is mounted into a P.C. board, pitch spacing should be aligned to prevent any stress to the resin. Any unsuitable stress applied to resin may break bonding wire in LED, which will cause failure.
- Protruded resin under flange is 1.5mm Max.
- Specifications are subject to change without notice.

**Absolute Maximum Rating**

Parameter	Maximum Rating	Unit
DC forward current	30	mA
Peak forward current Pulse width Max. 10ms duty ratio Max 1/10	100	mA
Reverse Voltage	5	V
Power dissipation	100	mW
Operating Temperature Range	- 40 °C to +85°C	
Storage Temperature Range	-40°C to +100°C	
Lead Soldering Temperature [4mm From Body]	260°C for 5 seconds	

**Electro-Optical Characteristics ( Ta=25°C )**

Parameter Radiant	Test Condition	Symbol	Min.	Typ	Max.	Unit
Forward Voltage	If=20mA	V <sub>DD</sub>	2.8	3.6	4.0	V
Color Temperature	If=20mA	C <sub>T</sub>			10000	K
Luminous Intensity	If=20mA	I <sub>v</sub>	80		110	cd
Reverse Current	V <sub>r</sub> =5V	I <sub>r</sub>			100	μA
Viewing Angle	If=20mA	2 θ 1/2		20		deg

